

Digital FET, N-Channel

KDV303N

Features

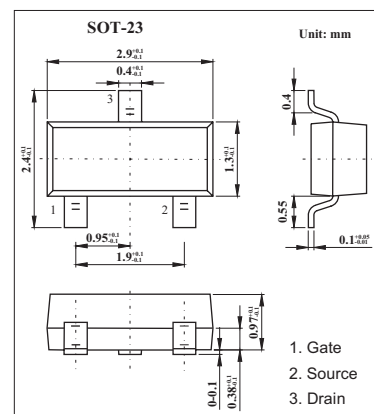
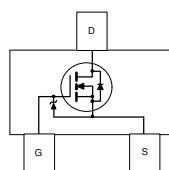
0.68 A, 25 V. $R_{DS(ON)} = 0.45 \Omega @ V_{GS} = 4.5 \text{ V}$

$R_{DS(ON)} = 0.6 \Omega @ V_{GS} = 2.7 \text{ V}$.

Very low level gate drive requirements allowing direct operation in 3V circuits. $V_{GS(th)} < 1.5 \text{ V}$.

Gate-Source Zener for ESD ruggedness.

6kV Human Body Model



Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Drain to Source Voltage	V_{DS}	25	V
Gate to Source Voltage	V_{GS}	8	V
Drain Current- Continuous	I_D	0.68	A
Drain Current- pulse		2	A
Power Dissipation for Single Operation	P_D	0.35	W
Operating and Storage Junction Temperature Range	T_J, T_{stg}	-55 to +150	$^\circ\text{C}$
Thermal Resistance, Junction-to- Ambient	$R_{\theta JA}$	357	$^\circ\text{C/W}$

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Electrical Characteristics Ta = 25°C

Parameter	Symbol	Testconditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	V _{DSS}	V _{GS} = 0 V, I _D = 250 μA	25			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 20 V, V _{GS} = 0 V			1	μA
		V _{DS} = 20 V, V _{GS} = 0 V, T _J = 55°C			10	μA
Gate-Body Leakage Current, Forward	I _{GSSF}	V _{GS} = 8V, V _{DS} = 0 V			100	nA
Gate-Body Leakage Current, Reverse	I _{GSSR}	V _{GS} = -8 V, V _{DS} = 0 V			-100	nA
Gate Threshold Voltage *	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA	0.65	0.8	1.5	V
Static Drain-Source On-Resistance*	R _{DS(on)}	V _{GS} = 4.5V, I _D = 0.5A		0.33	0.45	Ω
		V _{GS} = 4.5V, I _D = 0.2A, T _J = 125°C		0.52	0.8	Ω
		V _{GS} = 2.7V, I _D = 0.2 A		0.44	0.6	Ω
On-State Drain Current *	I _{D(on)}	V _{GS} = 2.7 V, V _{DS} = 5 V	0.5			A
Forward Transconductance *	g _{FS}	V _{DS} = 5V, I _D = 0.5 A		1.45		S
Input Capacitance	C _{iss}	V _{DS} = 10 V,		50		pF
Output Capacitance	C _{oss}	V _{GS} = 0 V,		28		pF
Reverse Transfer Capacitance	C _{rss}	f = 1.0 MHz		9		pF
Turn-On Delay Time	t _{d(on)}	V _{DD} = 6V, I _D = 0.5A,		3	6	ns
Turn-On Rise Time	t _r	V _{GS} = 4.5V, R _{GEN} = 50Ω		8.5	18	ns
Turn-Off Delay Time	t _{d(off)}			17	30	ns
Turn-Off Fall Time	t _f			13	25	ns
Total Gate Charge	Q _g	V _{DS} = 5 V, I _D = 0.5A,		1.64	2.3	nC
Gate-Source Charge	Q _{gs}	V _{GS} = 4.5V,		0.38		nC
Gate-Drain Charge	Q _{gd}			0.45		nC
Maximum Continuous Drain-Source Diode Forward Current	I _S				0.3	A
Drain-Source Diode Forward Voltage	V _{SD}	V _{GS} = 0 V, I _S = 0.5 A		0.83	1.2	V

* Pulse Test: Pulse Width 300μs, Duty Cycle 2.0%.

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Typical Characteristics

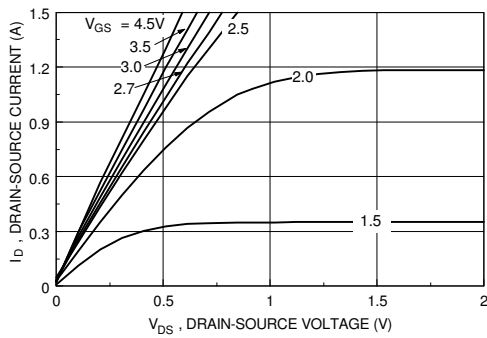


Figure 1. On-Region Characteristics.

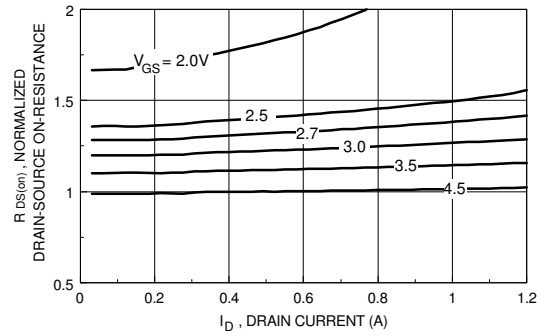


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

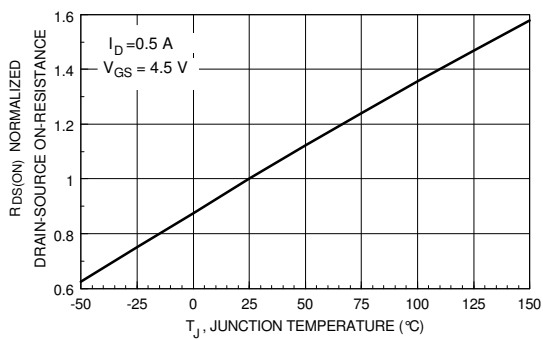


Figure 3. On-Resistance Variation with Temperature.

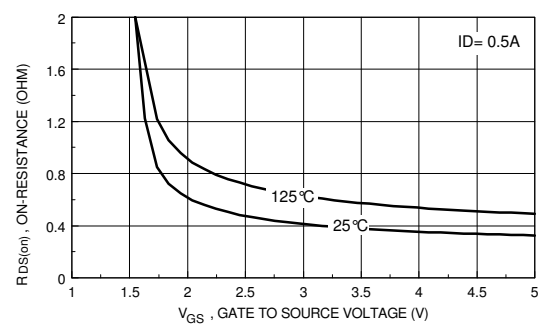


Figure 4. On Resistance Variation with Gate-To-Source Voltage.

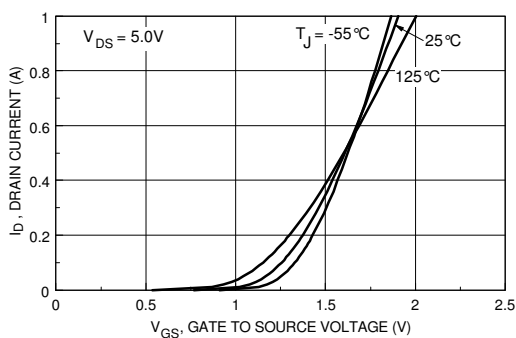


Figure 5. Transfer Characteristics.

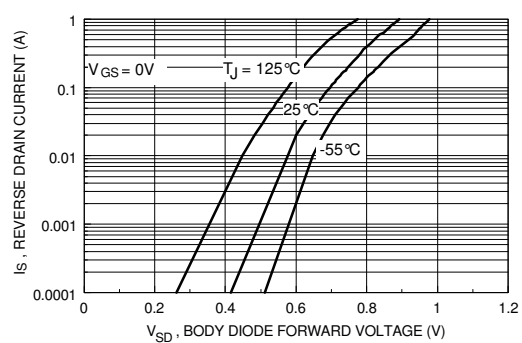


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

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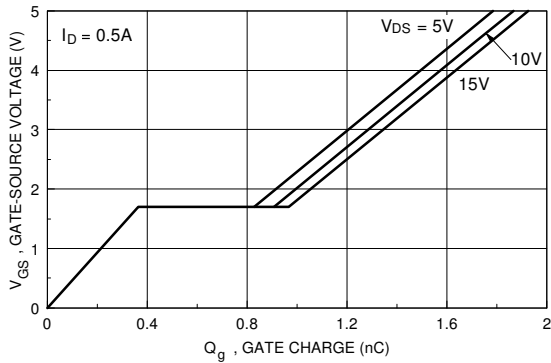


Figure 7. Gate Charge Characteristics.

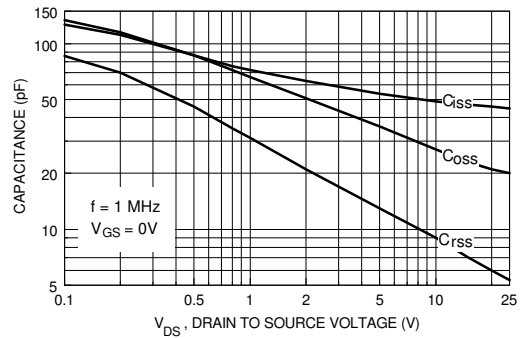


Figure 8. Capacitance Characteristics.

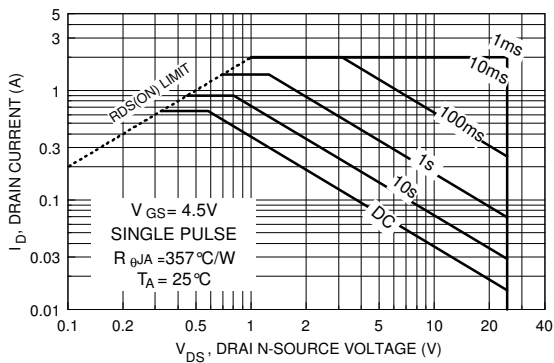


Figure 9. Maximum Safe Operating Area.

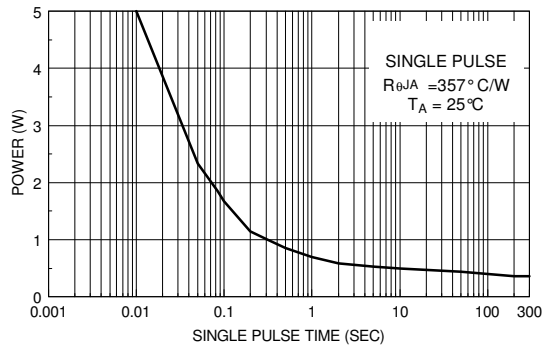


Figure 10. Single Pulse Maximum Power Dissipation.

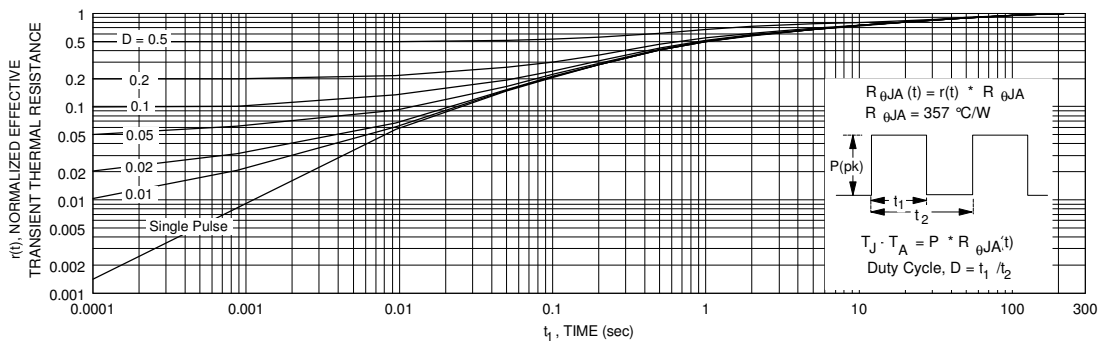


Figure 11. Transient Thermal Response Curve.